

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Security Agreement

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
PULSE ELECTRONICS CORPORATION		10/14/2011	CORPORATION: PENNSYLVANIA
PULSE ELECTRONICS, INC.	FORMERLY PULSE ENGINEERING, INC.	10/14/2011	CORPORATION: DELAWARE

RECEIVING PARTY DATA

Name:	JPMORGAN CHASE BANK, N.A., AS ADMINISTRATIVE AGENT
Street Address:	270 PARK AVENUE
City:	NEW YORK
State/Country:	NEW YORK
Postal Code:	10017
Entity Type:	ASSOCIATION: UNITED STATES

PROPERTY NUMBERS Total: 11

Property Type	Number	Word Mark
Registration Number:	1803124	VALOR
Registration Number:	2410114	Z-BLOCKER
Registration Number:	1921738	COPPERHEAD
Registration Number:	2441051	COMPONENTS FOR A MODERN WORLD
Serial Number:	85171998	
Serial Number:	85376672	MAGPAC
Serial Number:	85172007	PULSE ELECTRONICS
Serial Number:	85291715	SIDEWINDER
Serial Number:	75709982	EXCELSUS
Serial Number:	77434243	PULSE
Serial Number:	77434185	PULSE

CORRESPONDENCE DATA

900205637

**TRADEMARK
 REEL: 004649 FRAME: 0032**

OP \$290.00 1803124

Fax Number: (866)826-5420
Phone: 301-638-0511
Email: ipresearchplus@comcast.net

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: IP Research Plus, Inc.
Address Line 1: 21 Tadcaster Circle
Address Line 2: attn: Penelope J.A. Agodoa
Address Line 4: Waldorf, MARYLAND 20602

ATTORNEY DOCKET NUMBER:	37447
NAME OF SUBMITTER:	Penelope J.A. Agodoa
Signature:	/pja/
Date:	10/26/2011

Total Attachments: 12
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PATENT AND TRADEMARK SECURITY AGREEMENT dated as of October 14, 2011 (this "Agreement"), among Pulse Electronics Corporation (formerly known as Technitrol, Inc.) (the "Company"), the Subsidiaries party hereto (the "Subsidiary Grantors" and, collectively with the Company, the "Grantors") and JPMORGAN CHASE BANK, N.A. ("JPMCB"), as Administrative Agent.

Reference is made to (a) the Credit Agreement dated as of February 28, 2008, as amended and restated as of February 19, 2009 and as further amended and restated as of August 5, 2011, (as amended, supplemented or otherwise modified from time to time, the "Credit Agreement"), among the Company, the Lenders party thereto and JPMCB, as Administrative Agent, the Swing Line Lender and an L/C Issuer, and (b) the Domestic Collateral Agreement dated as of February 19, 2009 (as amended, supplemented or otherwise modified from time to time, the "Domestic Collateral Agreement"), among the Company, the Subsidiaries of the Company party thereto and JPMCB, as Administrative Agent (the "Administrative Agent"). The Lenders have heretofore extended credit to the Borrowers under the Credit Agreement, and the Lenders and the L/C Issuers have agreed to extend additional credit to the Borrowers under the Credit Agreement. The Grantors have entered into this Agreement in order to induce the Lenders and the L/C Issuers to make certain accommodations under the Credit Agreement and to continue to extend credit to the Borrowers. The obligation of the Lenders and the L/C Issuers to make such accommodations, and to continue to extend such credit, are conditioned upon, among other things, the execution and delivery of this Agreement. The Subsidiary Grantors are or are Affiliates of the Borrowers, will derive substantial benefits from such accommodations under the Credit Agreement and the extension of credit to the Borrowers pursuant to the Credit Agreement and are willing to execute and deliver this Agreement in order to induce the Lenders and the L/C Issuers to make additional extensions of credit under the Credit Agreement and as consideration for such extensions of credit and other accommodations under the Credit Agreement previously made. Accordingly, the parties hereto agree as follows:

SECTION 1. Defined Terms. Capitalized terms used in this Agreement and not otherwise defined herein have the meanings specified in the Domestic Collateral Agreement. The rules of construction specified in Section 1.02 of the Credit Agreement also apply to this Agreement, mutatis mutandis.

SECTION 2. Grant of Security Interest. As security for the payment or performance, as the case may be, in full of the Secured Obligations, each of the Grantors, pursuant to the Domestic Collateral Agreement, did and hereby does grant to the Administrative Agent, its successors and permitted assigns, for the benefit of the Secured Parties, a security interest in, all right, title and interest in and to any and all of the following assets and properties now owned or at any time hereafter acquired by such Grantor or in which such Grantor now has or at any time in the future may acquire any right, title or interest (collectively, the "Patent and Trademark Collateral"):

(a) all letters patent of the United States, all registrations and recordings thereof, and all applications for letters patent of the United States, including registrations, recordings and pending applications in the United States Patent and Trademark Office, including those registered Patents (as defined in the Domestic Collateral Agreement) and Patent applications listed on Schedule I (the "Patents");

(b) all reissues, continuations, divisions, continuations-in-part, renewals or extensions thereof, and the inventions disclosed or claimed therein, including the right to make, use and/or sell the inventions disclosed or claimed therein;

(c) all trademarks, service marks, trade names, corporate names, company names, business names, fictitious business names, trade styles, trade dress, logos, other source or business identifiers, designs and general intangibles of like nature, now existing or hereafter adopted or acquired, all registrations and recordings thereof, and all registration and recording applications filed in connection therewith, including registrations and registration applications in the United States Patent and Trademark Office or any similar offices in any State of the United States, and all extensions, or renewals thereof, including those United States registered Trademarks (as defined in the Domestic Collateral Agreement) and Trademark applications listed on Schedule II (the "Trademarks");

(d) all goodwill associated with the Trademarks or symbolized thereby;
and

(e) all other assets, rights and interests that uniquely reflect or embody such goodwill.

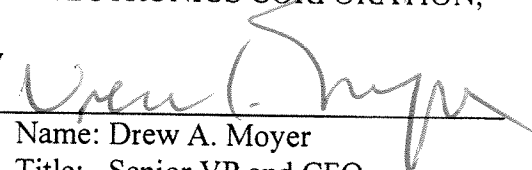
SECTION 3. Domestic Collateral Agreement. The security interests granted to the Administrative Agent herein are granted in furtherance, and not in limitation of, the security interests granted to the Administrative Agent pursuant to the Domestic Collateral Agreement. Each Grantor hereby acknowledges and affirms that the rights and remedies of the Administrative Agent with respect to the Patent and Trademark Collateral are more fully set forth in the Domestic Collateral Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Domestic Collateral Agreement, the terms of the Domestic Collateral Agreement shall govern.

SECTION 4. Governing Law. This Agreement shall be construed in accordance with and governed by the law of the State of New York.

IN WITNESS WHEREOF, the parties hereto have duly executed this Patent and Trademark Security Agreement as of the day and year first above written.

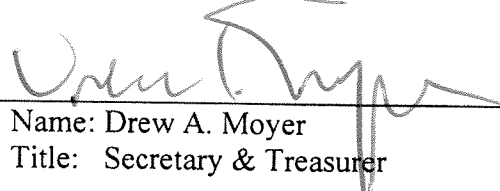
PULSE ELECTRONICS CORPORATION,

By


Name: Drew A. Moyer
Title: Senior VP and CFO

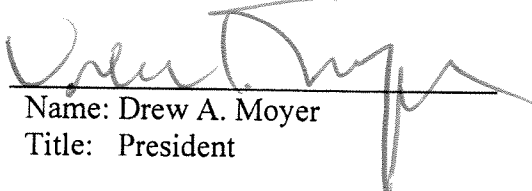
PULSE ELECTRONICS, INC.,

By


Name: Drew A. Moyer
Title: Secretary & Treasurer

TECHNITROL DELAWARE, INC.,

By


Name: Drew A. Moyer
Title: President

JPMORGAN CHASE BANK, N.A., as
Administrative Agent, on behalf of itself and
the other Secured Parties,







By 


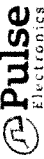




Name: Deborah R. Winkler
Title: Vice President



SCHEDULE 1

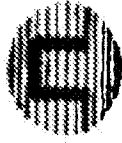

Patent or Application #	Owner of Patent	Title	Patent Granted (countries)	Patent Apps Pending (countries)	Patent Grant Date	Patent Expiration Date
61/413,913	Pulse Engineering, Inc.	Advanced Electronic Header Apparatus and Methods		US	None	None
12/012,157	Pulse Engineering, Inc.	Self-Leaded Surface Mount Inductors and Methods		US	None	None
12/567,622	Pulse Engineering, Inc.	Current Sensing Devices and Methods		US, PCT, TW	None	None
12/684,056	Pulse Engineering, Inc.	Current Sensing Devices and Methods		US, PCT, TW	None	None
12/954,546	Pulse Engineering, Inc.	Current Sensing Devices and Methods		US, PCT, TW	None	None
5,262,745	Pulse Engineering, Inc.	Surface mounted multi-section bobbin	US		11/16/1993	1/27/2012
5,971,805	Co-owned: Pulse Engineering, Inc. & Berg Inc.	Modular jack with filter insert	US		10/26/1999	5/27/2017
6,005,467	Pulse Engineering, Inc.	Trimmable Inductor	US		12/21/1999	1/21/2008
6,181,777	Pulse Engineering, Inc.	Impedance Blocking Filter Circuit	US		12/19/2006	11/19/2018
6,087,920	Pulse Engineering, Inc.	Monolithic Inductor	US		7/11/2000	8/11/2008
6,087,921	Pulse Engineering, Inc.	Placement Insensitive Monolithic Inductor And Method Of Manufacturing Same	US		7/11/2000	8/11/2008
6,193,560	Co-owned: Pulse Engineering, Inc. & Tyco Inc.	Connector assembly with side-by-side terminal arrays	US		2/27/2001	3/3/2020
6,504,906	Pulse Engineering, Inc.	Telephone Micro-tester & Signature Transport System	US		1/7/2003	2/7/2007
6,628,531	Pulse Engineering, Inc.	Multi-Layer, User-Configurable Micro-Printed Circuit Board	US	CN, TW	9/30/2003	1/24/2021
6,872,098	Co-owned: Pulse Engineering, Inc. & Tyco Inc.	Modular jack assembly with signal conditioning	US		3/29/2005	7/31/2022
7,661,994	Pulse Engineering, Inc.	Universal connector assembly and method of manufacturing	US		2/16/2010	5/5/2028
7,786,009	Pulse Engineering, Inc.	Universal connector assembly and method of manufacturing	US		8/31/2010	2/15/2030
7,845,975	Pulse Engineering, Inc.	Low-profile connector assembly and methods	US	CN, TW	12/7/2010	1/29/2028
7,845,984	Pulse Engineering, Inc.	Integrated 2x6 with POE controller "Backpack"	US		12/7/2010	6/30/2029
7,876,189	Pulse Engineering, Inc.	Form-less Electronic device and methods of manufacture	US	CN	1/25/2011	7/6/2024
7,942,700	Pulse Engineering, Inc.	Modular electronic header assembly and methods of manufacture	US	TW	5/17/2011	5/10/2030
7,959,473	Pulse Engineering, Inc.	Universal connector assembly and method of manufacturing	US		6/14/2011	8/30/2030
7,982,572	Pulse Engineering, Inc.	MicroTransformer MagPac	US		7/19/2011	7/15/2029
RE40,020	Pulse Engineering, Inc.	Impedance Blocking Filter Circuit	US		1/22/2008	11/19/2018
RE41,145	Pulse Engineering, Inc.	Impedance Blocking Filter Circuit	US		2/23/2010	11/19/2018
RE41,164	Pulse Engineering, Inc.	Impedance Blocking Filter Circuit	US		3/16/2010	10/22/2019

SCHEDULE 2

Country	Trademark	Image	Application Number/ Application Date	Registration Number/ Registration Date	Class	Owner	Status/Remarks
Intl Reg.	Design Only		85171998	1088559 05-May-2011	9, 42	Pulse Electronics Corporation	Registration (Registered)/ International Registration designating: Australia, European Community, Japan, Norway, Russian Federation, Singapore and Switzerland.
Korea	Design Only		45-2011- 0001928 06-May-2011		9, 42	Pulse Electronics Corporation	Unpublished Application (Pending)
USA	Design Only		85171998 08-Nov-2010		9, 40, 42	Pulse Electronics Corporation	Pending Intent To Use (Final Refusal Mailed 7/26/11)
China	Design Only		9437159 09-May-2011		9	Pulse Electronics Corporation	Pending
China	Design Only		9437158 09-May-2011		42	Pulse Electronics Corporation	Pending
Taiwan	Design Only		100022555 06-May-2011		9, 42	Pulse Electronics Corporation	Pending
USA	MAGPAC	MagPac	85376672 20-Jul-2011		9	Pulse Electronics Corporation	Pending Intent To Use

Country	Trademark	Image	Application Number/ Application Date	Registration Number/ Registration Date	Class	Owner	Status/Remarks
Intl Reg.	Pulse Electronics			1086937 05-May-2011	9, 42	Pulse Electronics Corporation	Registration (Registered)/ International Registration designating: Australia, European Community, Japan, Norway, Russian Federation, Singapore and Switzerland.
Korea	PULSE ELECTRONICS		45-2011- 0001929 06-May-2011		9, 42	Pulse Electronics Corporation	Unpublished Application (Pending)
USA	PULSE ELECTRONICS		85172007 08-Nov-2010		9, 40, 42	Pulse Electronics Corporation	Pending Intent To Use (Final Refusal Mailed 7/28/11)
China	PULSE ELECTRONICS		9461086 13-May-2011		40	Pulse Electronics Corporation	Pending
Taiwan	PULSE ELECTRONICS		100022554 06-May-2011		9, 42	Pulse Electronics Corporation	Pending
USA	SIDEWINDER		85291715 11-Apr-2011		9	Pulse Electronics Corporation	Published (Pending) Intent To Use
USA	EXCELSUS		75709982 20-May-1999	2432883 06-Mar-2001	9	Pulse Electronics, Inc.	Renewed (Registered)

Country	Trademark	Image	Application Number/ Application Date	Registration Number/ Registration Date	Class	Owner	Status/Remarks
Intl Reg.	PULSE			989855 29-Sep-2008	9, 10, 40, 42	Pulse Electronics, Inc.	Registration (Registered)/ International Registration designating: Australia, China, European Community, Japan, Korea, Norway, Russian Federation, Singapore and Switzerland. (Total refusal in Australia and Korea).
Intl Reg.	Pulse			989856 29-Sep-2008	9, 10, 40, 42	Pulse Electronics, Inc.	Registration (Registered) International Registration designating: Australia, China, European Community, Japan, Korea, Norway, Russian Federation, Singapore and Switzerland. (Total refusal in Australia and Korea).
USA	PULSE		77434243 08-Nov-2010		9, 10, 40, 42	Pulse Electronics, Inc.	Pending Intent To Use Suspended
USA	PULSE	PULSE	77434185 28-Mar-2008		9, 10, 40, 42	Pulse Electronics, Inc.	Pending Intent To Use Suspended
Taiwan	LARSEN		83049681 28-Jul-1994	682719 01-Jul-1995	9	Pulse Engineering, Inc.	Registration (Registered)

Country	Trademark	Image	Application Number/ Application Date	Registration Number/ Registration Date	Class	Owner	Status/Remarks
Denmark	PULSE		VA 003814 2008 26-Sep-2008	VR 001275 2009 04-May-2009	9, 10, 40, 42	Pulse Electronics, Inc.	Registration (Registered)
USA	VALOR		74304761 13-Aug-1992	1803124 09-Nov-1993	9	Pulse Electronics, Inc.	Renewed (Registered)
USA	Z-BLOCKER		75706173 13-May-1999	2410114 05-Dec-2000	9	Pulse Electronics, Inc.	Renewed (Registered)
China	Design Only		3332174 10-Oct-2002	3332174 28-Oct-2003	9	Pulse Engineering, Inc.	Registration (Registered)
China	MGTOROID	MGTOROID	3001706 23-Oct-2001	3001706 14-Feb-2003	9	Pulse Engineering, Inc.	Registration (Registered)
China	PULSE		6097480 08-Jun-2007		9	Pulse Engineering, Inc.	Unpublished Application (Pending)
China	YOUR BUILD TO PRINT PARTNER		1947832 26-Feb-2001	1947832 07-Jan-2003	40	Pulse Engineering, Inc.	Registration (Registered) (To Be Abandoned)
China	WEILI MAGNETICS	WEILI MAGNETICS	1947843 26-Feb-2001	1947843 07-Jan-2003	40	Pulse Engineering, Inc.	Registration (Registered) (To Be Abandoned)
USA	COPPERHEAD		74576554 21-Sep-1994	1921738 26-Sep-1995	9	Pulse Engineering, Inc.	Renewed (Registered)

Country	Trademark	Image	Application Number/ Application Date	Registration Number/ Registration Date	Class	Owner	Status/Remarks
USA	COMPONENTS FOR A MODERN WORLD		76038699 02-May-2000	2441051 03-Apr-2001	40	Pulse Electronics Corporation	Registered